



## Superior™ F850 Technical Information

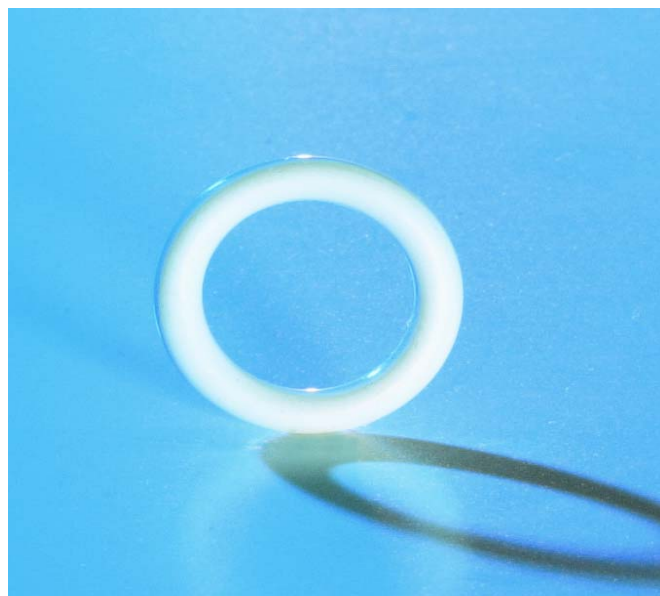
Superior F850 was specifically developed to be a cost-effective, high-performance compound for semiconductor applications. Superior F850 offers outstanding plasma resistance and low particulation in a wide range of plasma environments.

### Features and Benefits

- Outstanding plasma resistance
- Minimum particulation
- Wide chemical resistance
- High physical properties
- Cost-effective

### Recommended Processes

- Deposition: CVD, APCVD, HDPCVD, RPCVD, SACVD
- Plasma etch: poly, oxide and metal
- Ashing
- Metalization: PVD, sputtering
- Ion Implant



**Off-White Specialty Fluoroelastomer**  
**Service Temperature Range: -15°C to 200°C**

### Equipment Locations

- Chamber Lid Seals
- Bell Jar Seals
- Endpoint Windows
- Gas Inlet Seals
- Isolator Valve Seals
- KF Fittings
- Slit Valve Seals
- Valve Seals
- Window Seals

### Typical Physical Properties

Color	Off-White
Hardness, Shore A	85
Tensile Strength, PSI (MPa)	3920 (27)
Elongation	330%
Modulus @ 100% Elongation, PSI (MPa)	915 (6.3)
Compression Set: 70 hrs @175°C	22%
Service Temperature Range, °C (°F)	-15 to 200 (5 to 390)